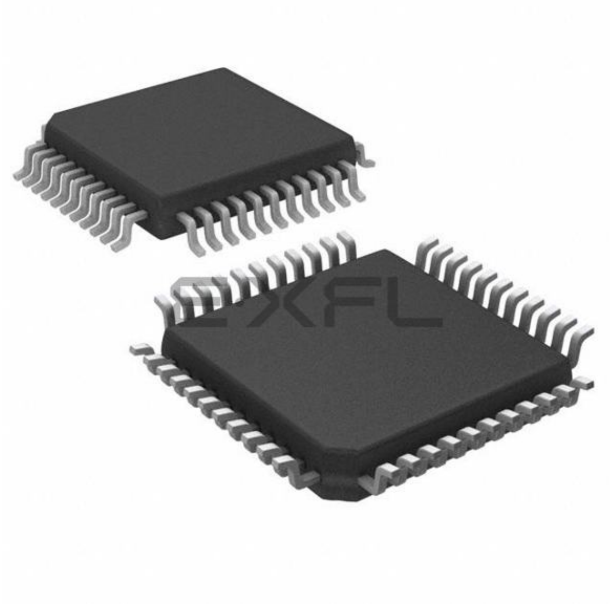


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	368 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-QFP
Supplier Device Package	44-MQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf877t-04i-pq

NOTES:

2.2.2.2 OPTION_REG Register

The OPTION_REG Register is a readable and writable register, which contains various control bits to configure the TMR0 prescaler/WDT postscaler (single assignable register known also as the prescaler), the External INT Interrupt, TMR0 and the weak pull-ups on PORTB.

> **Note:** To achieve a 1:1 prescaler assignment for the TMR0 register, assign the prescaler to the Watchdog Timer.

REGISTER 2-2: OPTION_REG REGISTER (ADDRESS 81h, 181h)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0
bit 7							bit 0

bit 7 **$\overline{\text{RBPU}}$:** PORTB Pull-up Enable bit
1 = PORTB pull-ups are disabled
0 = PORTB pull-ups are enabled by individual port latch values

bit 6 **INTEDG**: Interrupt Edge Select bit
1 = Interrupt on rising edge of RB0/INT pin
0 = Interrupt on falling edge of RB0/INT pin

bit 5 **T0CS**: TMR0 Clock Source Select bit
1 = Transition on RA4/T0CKI pin
0 = Internal instruction cycle clock (CLKOUT)

bit 4 **T0SE**: TMR0 Source Edge Select bit
1 = Increment on high-to-low transition on RA4/T0CKI pin
0 = Increment on low-to-high transition on RA4/T0CKI pin

bit 3 **PSA**: Prescaler Assignment bit
1 = Prescaler is assigned to the WDT
0 = Prescaler is assigned to the Timer0 module

bit 2-0 **PS2:PS0**: Prescaler Rate Select bits

Bit Value	TMR0 Rate	WDT Rate
000	1 : 2	1 : 1
001	1 : 4	1 : 2
010	1 : 8	1 : 4
011	1 : 16	1 : 8
100	1 : 32	1 : 16
101	1 : 64	1 : 32
110	1 : 128	1 : 64
111	1 : 256	1 : 128

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
- n = Value at POR	’1’ = Bit is set	’0’ = Bit is cleared	x = Bit is unknown

Note: When using low voltage ICSP programming (LVP) and the pull-ups on PORTB are enabled, bit 3 in the TRISB register must be cleared to disable the pull-up on RB3 and ensure the proper operation of the device

2.2.2.8 PCON Register

The Power Control (PCON) Register contains flag bits to allow differentiation between a Power-on Reset (POR), a Brown-out Reset (BOR), a Watchdog Reset (WDT), and an external $\overline{\text{MCLR}}$ Reset.

Note:	$\overline{\text{BOR}}$ is unknown on POR. It must be set by the user and checked on subsequent RESETS to see if BOR is clear, indicating a brown-out has occurred. The BOR status bit is a “don’t care” and is not predictable if the brown-out circuit is disabled (by clearing the BODEN bit in the configuration word).

REGISTER 2-8: PCON REGISTER (ADDRESS 8Eh)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-1
—	—	—	—	—	—	$\overline{\text{POR}}$	$\overline{\text{BOR}}$
bit 7							bit 0

bit 7-2 **Unimplemented:** Read as '0'

bit 1 $\overline{\textbf{POR}}$: Power-on Reset Status bit
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0 $\overline{\textbf{BOR}}$: Brown-out Reset Status bit
1 = No Brown-out Reset occurred
0 = A Brown-out Reset occurred (must be set in software after a Brown-out Reset occurs)

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
- n = Value at POR	’1’ = Bit is set	’0’ = Bit is cleared	x = Bit is unknown

TABLE 3-5: PORTC FUNCTIONS

Name	Bit#	Buffer Type	Function
RC0/T1OSO/T1CKI	bit0	ST	Input/output port pin or Timer1 oscillator output/Timer1 clock input.
RC1/T1OSI/CCP2	bit1	ST	Input/output port pin or Timer1 oscillator input or Capture2 input/ Compare2 output/PWM2 output.
RC2/CCP1	bit2	ST	Input/output port pin or Capture1 input/Compare1 output/ PWM1 output.
RC3/SCK/SCL	bit3	ST	RC3 can also be the synchronous serial clock for both SPI and I^2C modes.
RC4/SDI/SDA	bit4	ST	RC4 can also be the SPI Data In (SPI mode) or data I/O (I^2C mode).
RC5/SDO	bit5	ST	Input/output port pin or Synchronous Serial Port data output.
RC6/TX/CK	bit6	ST	Input/output port pin or USART Asynchronous Transmit or Synchronous Clock.
RC7/RX/DT	bit7	ST	Input/output port pin or USART Asynchronous Receive or Synchronous Data.

Legend: ST = Schmitt Trigger input

TABLE 3-6: SUMMARY OF REGISTERS ASSOCIATED WITH PORTC

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other RESETS
07h	PORTC	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	`xxxx xxxx`	`uuuu uuuu`
87h	TRISC	PORTC Data Direction Register								`1111 1111`	`1111 1111`

Legend: `x` = unknown, `u` = unchanged

REGISTER 8-1: CCP1CON REGISTER/CCP2CON REGISTER (ADDRESS: 17h/1Dh)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	CCPxX	CCPxY	CCPxM3	CCPxM2	CCPxM1	CCPxM0
bit 7							bit 0

bit 7-6 **Unimplemented:** Read as '0'

bit 5-4 **CCPxX:CCPxY**: PWM Least Significant bits

Capture mode:
Unused

Compare mode:
Unused

PWM mode:
These bits are the two LSbs of the PWM duty cycle. The eight MSbs are found in CCPRxL.

bit 3-0 **CCPxM3:CCPxM0**: CCPx Mode Select bits

`0000` = Capture/Compare/PWM disabled (resets CCPx module)
`0100` = Capture mode, every falling edge
`0101` = Capture mode, every rising edge
`0110` = Capture mode, every 4th rising edge
`0111` = Capture mode, every 16th rising edge
`1000` = Compare mode, set output on match (CCPxIF bit is set)
`1001` = Compare mode, clear output on match (CCPxIF bit is set)
`1010` = Compare mode, generate software interrupt on match (CCPxIF bit is set, CCPx pin is unaffected)
`1011` = Compare mode, trigger special event (CCPxIF bit is set, CCPx pin is unaffected); CCP1 resets TMR1; CCP2 resets TMR1 and starts an A/D conversion (if A/D module is enabled)
`11xx` = PWM mode

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
- n = Value at POR	’1’ = Bit is set	’0’ = Bit is cleared	x = Bit is unknown

NOTES:

REGISTER 9-3: SSPCON2: SYNC SERIAL PORT CONTROL REGISTER2 (ADDRESS 91h)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
GCEN	ACKSTAT	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN
bit 7							bit 0

bit 7 **GCEN**: General Call Enable bit (In I^{2}C Slave mode only)
1 = Enable interrupt when a general call address (0000h) is received in the SSPSR
0 = General call address disabled

bit 6 **ACKSTAT**: Acknowledge Status bit (In I^{2}C Master mode only)
In Master Transmit mode:
1 = Acknowledge was not received from slave
0 = Acknowledge was received from slave

bit 5 **ACKDT**: Acknowledge Data bit (In I^{2}C Master mode only)
In Master Receive mode:
Value that will be transmitted when the user initiates an Acknowledge sequence at the end of a receive.
1 = Not Acknowledge
0 = Acknowledge

bit 4 **ACKEN**: Acknowledge Sequence Enable bit (In I^{2}C Master mode only)
In Master Receive mode:
1 = Initiate Acknowledge sequence on SDA and SCL pins and transmit ACKDT data bit. Automatically cleared by hardware.
0 = Acknowledge sequence idle

bit 3 **RCEN**: Receive Enable bit (In I^{2}C Master mode only)
1 = Enables Receive mode for I^{2}C
0 = Receive idle

bit 2 **PEN**: STOP Condition Enable bit (In I^{2}C Master mode only)
SCK Release Control:
1 = Initiate STOP condition on SDA and SCL pins. Automatically cleared by hardware.
0 = STOP condition idle

bit 1 **RSEN**: Repeated START Condition Enable bit (In I^{2}C Master mode only)
1 = Initiate Repeated START condition on SDA and SCL pins. Automatically cleared by hardware.
0 = Repeated START condition idle

bit 0 **SEN**: START Condition Enable bit (In I^{2}C Master mode only)
1 = Initiate START condition on SDA and SCL pins. Automatically cleared by hardware.
0 = START condition idle

Note: For bits ACKEN, RCEN, PEN, RSEN, SEN: If the I^{2}C module is not in the IDLE mode, this bit may not be set (no spooling), and the SSPBUF may not be written (or writes to the SSPBUF are disabled).

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
- n = Value at POR	’1’ = Bit is set	’0’ = Bit is cleared	x = Bit is unknown

9.1.2 SLAVE MODE

In Slave mode, the data is transmitted and received as the external clock pulses appear on SCK. When the last bit is latched, the interrupt flag bit SSPIF (PIR1<3>) is set.

While in Slave mode, the external clock is supplied by the external clock source on the SCK pin. This external clock must meet the minimum high and low times as specified in the electrical specifications.

While in SLEEP mode, the slave can transmit/receive data. When a byte is received, the device will wake-up from SLEEP.

Note 1: When the $\overline{\text{SPI}}$ module is in Slave mode with $\overline{\text{SS}}$ pin control enabled (SSPCON<3:0> = `0100`), the SPI module will reset if the $\overline{\text{SS}}$ pin is set to V_{DD}.

2: If the SPI is used in Slave mode with CKE = '1', then $\overline{\text{SS}}$ pin control must be enabled.

FIGURE 9-3: SPI MODE TIMING (SLAVE MODE WITH CKE = 0)

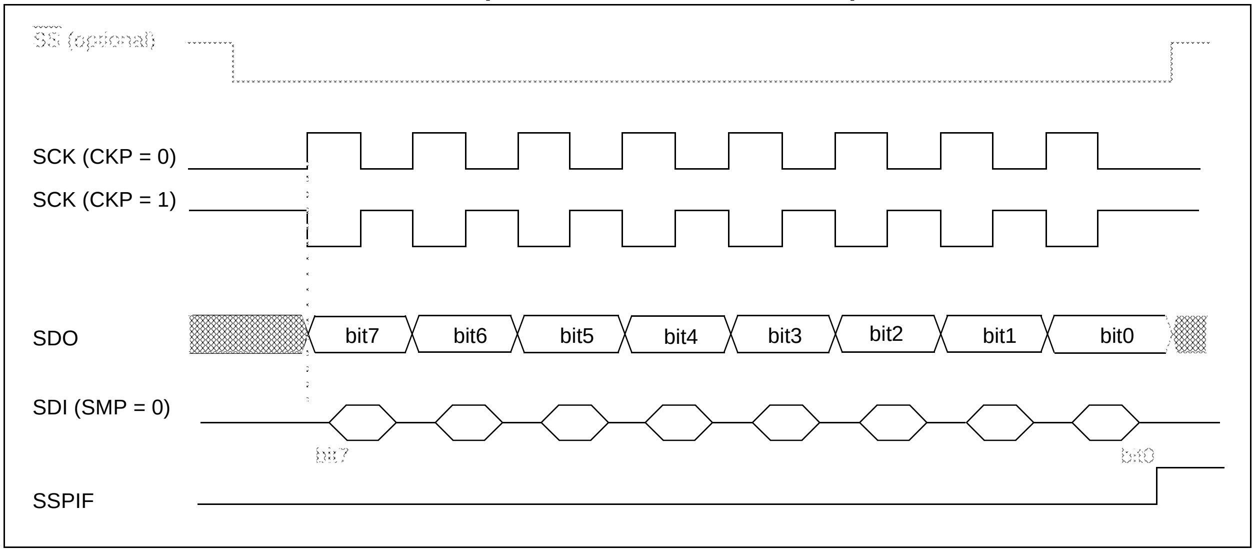
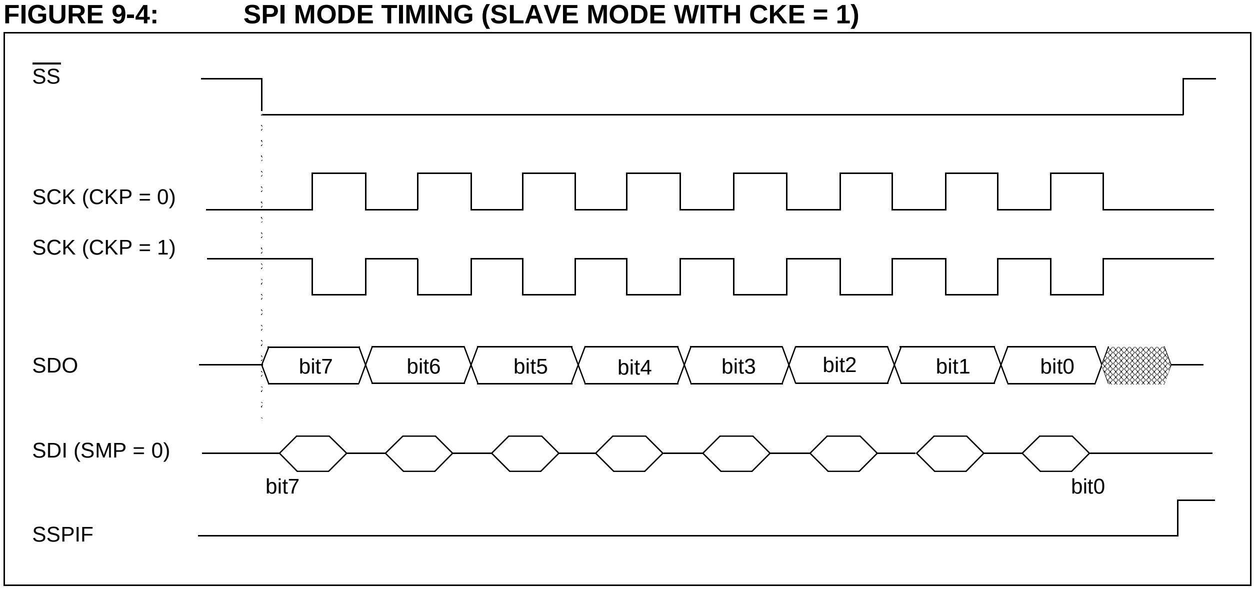


FIGURE 9-4: SPI MODE TIMING (SLAVE MODE WITH CKE = 1)

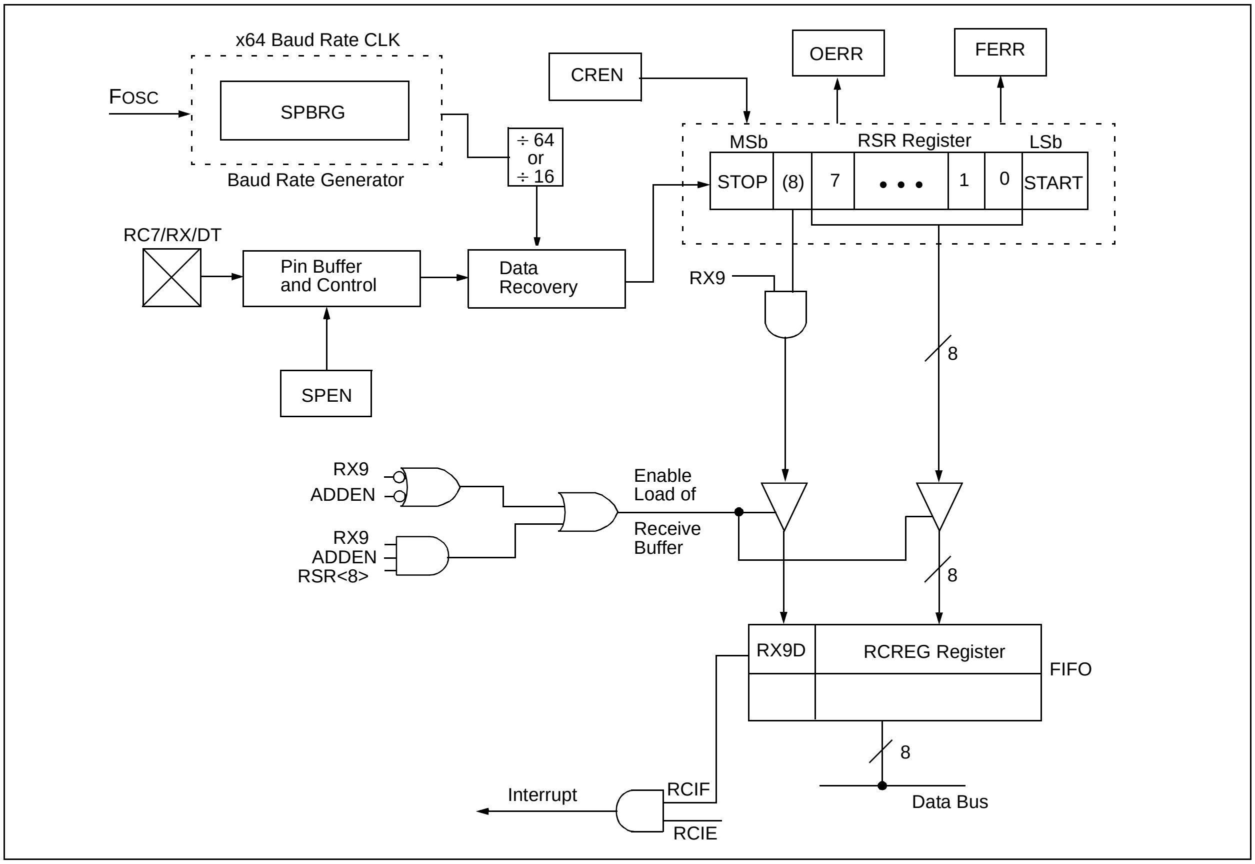


10.2.3 SETTING UP 9-BIT MODE WITH ADDRESS DETECT

When setting up an Asynchronous Reception with Address Detect Enabled:

- Initialize the SPBRG register for the appropriate baud rate. If a high speed baud rate is desired, set bit BRGH.
- Enable the asynchronous serial port by clearing bit SYNC and setting bit SPEN.
- If interrupts are desired, then set enable bit RCIE.
- Set bit RX9 to enable 9-bit reception.
- Set ADDEN to enable address detect.
- Enable the reception by setting enable bit CREN.
- Flag bit RCIF will be set when reception is complete, and an interrupt will be generated if enable bit RCIE was set.
- Read the RCSTA register to get the ninth bit and determine if any error occurred during reception.
- Read the 8-bit received data by reading the RCREG register, to determine if the device is being addressed.
- If any error occurred, clear the error by clearing enable bit CREN.
- If the device has been addressed, clear the ADDEN bit to allow data bytes and address bytes to be read into the receive buffer, and interrupt the CPU.

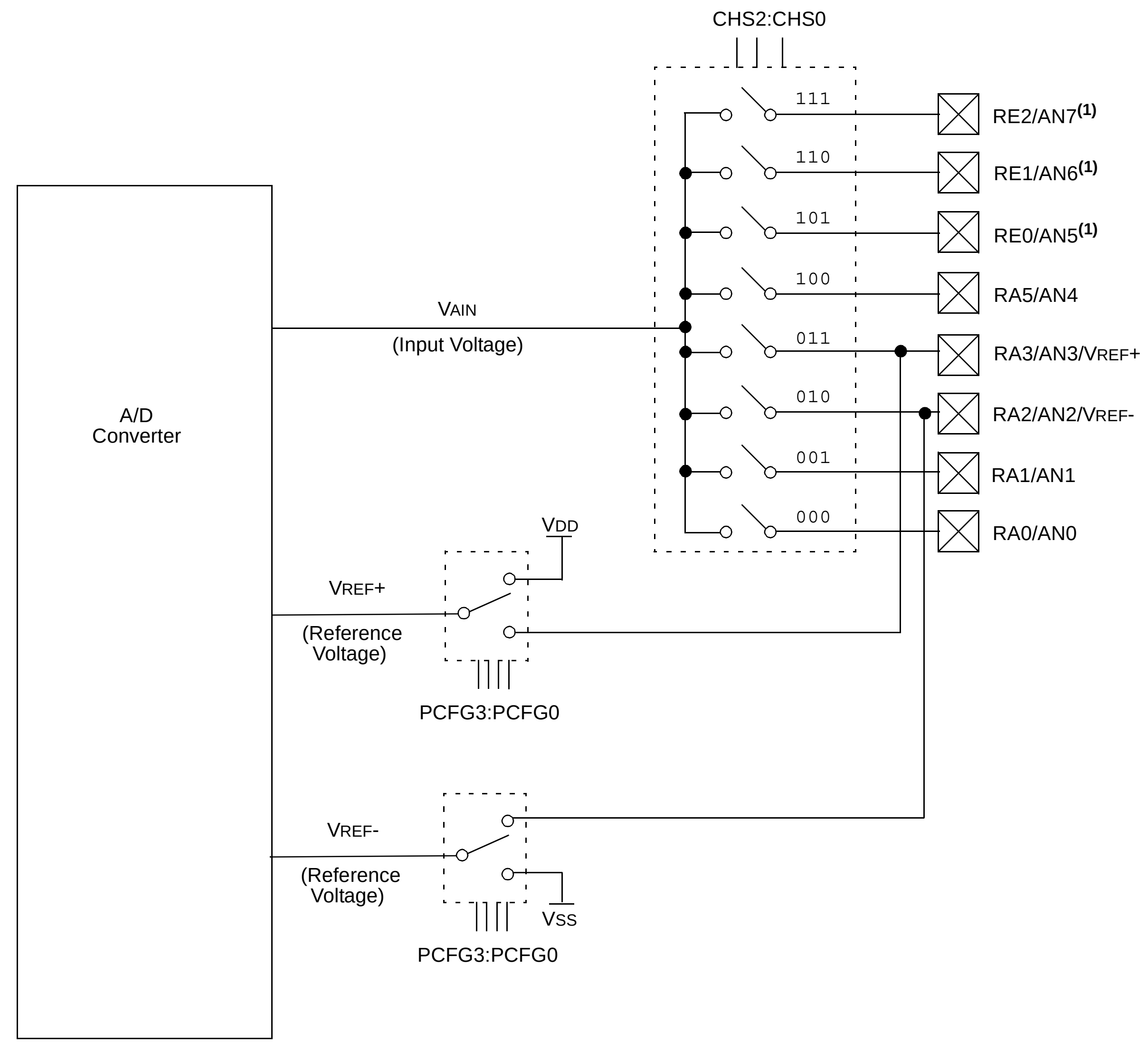
FIGURE 10-6: USART RECEIVE BLOCK DIAGRAM



These steps should be followed for doing an A/D Conversion:

1. Configure the A/D module:
   - Configure analog pins/voltage reference and digital I/O (ADCON1)
   - Select A/D input channel (ADCON0)
   - Select A/D conversion clock (ADCON0)
   - Turn on A/D module (ADCON0)
2. Configure A/D interrupt (if desired):
   - Clear ADIF bit
   - Set ADIE bit
   - Set PEIE bit
   - Set GIE bit
3. Wait the required acquisition time.
4. Start conversion:
   - Set GO/$\overline{\text{DONE}}$ bit (ADCON0)
5. Wait for A/D conversion to complete, by either:
   - Polling for the GO/$\overline{\text{DONE}}$ bit to be cleared (with interrupts enabled); OR
   - Waiting for the A/D interrupt
6. Read A/D result register pair (ADRESH:ADRESL), clear bit ADIF if required.
7. For the next conversion, go to step 1 or step 2, as required. The A/D conversion time per bit is defined as T_{AD}. A minimum wait of $2T_{AD}$ is required before the next acquisition starts.

FIGURE 11-1: A/D BLOCK DIAGRAM



Note 1: Not available on PIC16F873/876 devices.

11.5 A/D Operation During SLEEP

The A/D module can operate during SLEEP mode. This requires that the A/D clock source be set to RC (ADCS1:ADCS0 = `11`). When the RC clock source is selected, the A/D module waits one instruction cycle before starting the conversion. This allows the `SLEEP` instruction to be executed, which eliminates all digital switching noise from the conversion. When the conversion is completed, the GO/$\overline{\text{DONE}}$ bit will be cleared and the result loaded into the ADRES register. If the A/D interrupt is enabled, the device will wake-up from SLEEP. If the A/D interrupt is not enabled, the A/D module will then be turned off, although the ADON bit will remain set.

When the A/D clock source is another clock option (not RC), a `SLEEP` instruction will cause the present conversion to be aborted and the A/D module to be turned off, though the ADON bit will remain set.

Turning off the A/D places the A/D module in its lowest current consumption state.

Note: For the A/D module to operate in SLEEP, the A/D clock source must be set to RC (ADCS1:ADCS0 = `11`). To allow the conversion to occur during SLEEP, ensure the `SLEEP` instruction immediately follows the instruction that sets the GO/$\overline{\text{DONE}}$ bit.

11.6 Effects of a RESET

A device RESET forces all registers to their RESET state. This forces the A/D module to be turned off, and any conversion is aborted. All A/D input pins are configured as analog inputs.

The value that is in the ADRESH:ADRESL registers is not modified for a Power-on Reset. The ADRESH:ADRESL registers will contain unknown data after a Power-on Reset.

TABLE 11-2: REGISTERS/BITS ASSOCIATED WITH A/D

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on $\overline{\text{MCLR}}$, WDT
0Bh,8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
8Ch	PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
1Eh	ADRESH	A/D Result Register High Byte								xxxx xxxx	uuuu uuuu
9Eh	ADRESL	A/D Result Register Low Byte								xxxx xxxx	uuuu uuuu
1Fh	ADCON0	ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	—	ADON	0000 00-0	0000 00-0
9Fh	ADCON1	ADFM	—	—	—	PCFG3	PCFG2	PCFG1	PCFG0	--0- 0000	--0- 0000
85h	TRISA	—	—	PORTA Data Direction Register						--11 1111	--11 1111
05h	PORTA	—	—	PORTA Data Latch when written: PORTA pins when read						--0x 0000	--0u 0000
89h(1)	TRISE	IBF	OBF	IBOV	PSPMODE	—	PORTE Data Direction bits			0000 -111	0000 -111
09h(1)	PORTE	—	—	—	—	—	RE2	RE1	RE0	---- -xxx	---- -uuu

Legend: `x` = unknown, `u` = unchanged, `-` = unimplemented, read as '0'. Shaded cells are not used for A/D conversion.

Note 1: These registers/bits are not available on the 28-pin devices.

12.3 RESET

The PIC16F87X differentiates between various kinds of RESET:

- Power-on Reset (POR)
- $\overline{\text{MCLR}}$ Reset during normal operation
- $\overline{\text{MCLR}}$ Reset during SLEEP
- WDT Reset (during normal operation)
- WDT Wake-up (during SLEEP)
- Brown-out Reset (BOR)

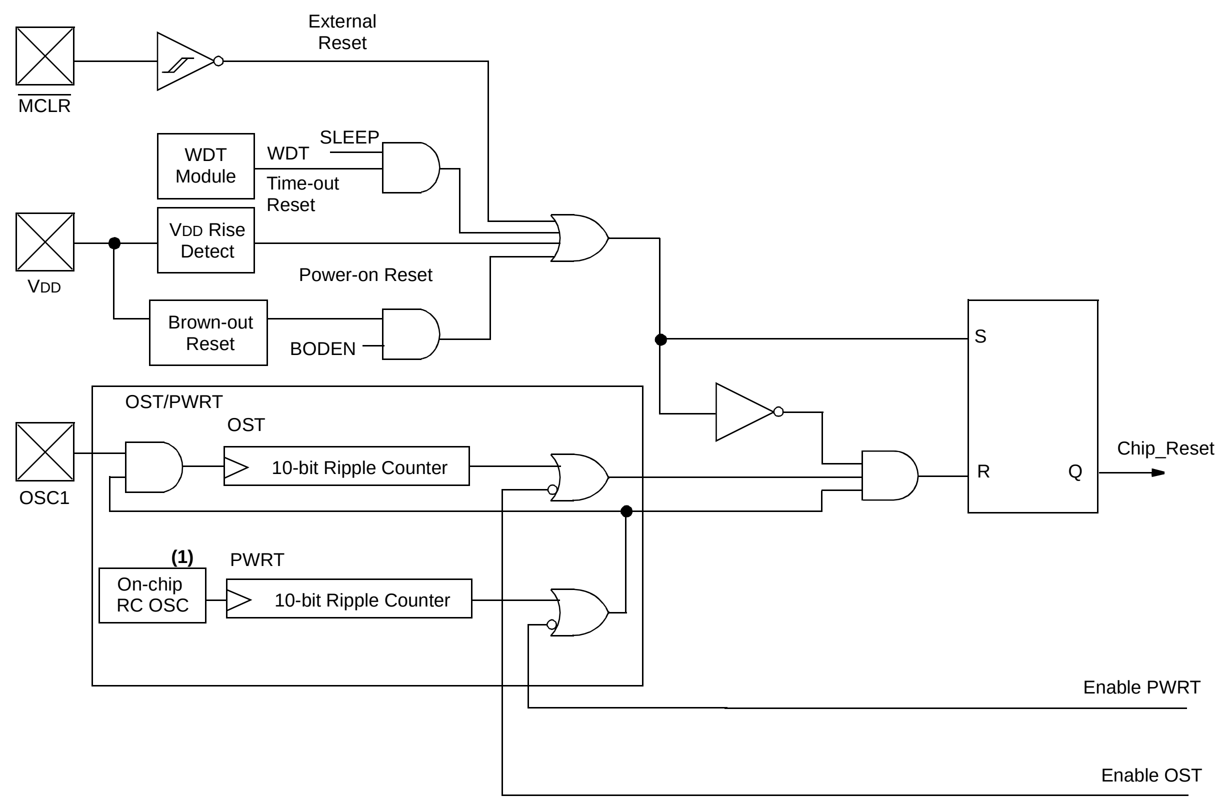
Some registers are not affected in any RESET condition. Their status is unknown on POR and unchanged in any other RESET. Most other registers are reset to a "RESET state" on Power-on Reset (POR), on the $\overline{\text{MCLR}}$ and WDT Reset, on $\overline{\text{MCLR}}$ Reset during SLEEP, and Brown-out Reset (BOR). They are not affected by a WDT Wake-up, which is viewed as the resumption of normal operation. The $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits are set or cleared differently in different RESET situations as indicated in Table 12-4. These bits are used in software to determine the nature of the RESET. See Table 12-6 for a full description of RESET states of all registers.

A simplified block diagram of the On-Chip Reset Circuit is shown in Figure 12-4.

These devices have a $\overline{\text{MCLR}}$ noise filter in the $\overline{\text{MCLR}}$ Reset path. The filter will detect and ignore small pulses.

It should be noted that a WDT Reset does not drive $\overline{\text{MCLR}}$ pin low.

FIGURE 12-4: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



Note 1: This is a separate oscillator from the RC oscillator of the CLKIN pin.

12.4 Power-On Reset (POR)

A Power-on Reset pulse is generated on-chip when V_{DD} rise is detected (in the range of 1.2V - 1.7V). To take advantage of the POR, tie the $\overline{MCLR}$ pin directly (or through a resistor) to V_{DD}. This will eliminate external RC components usually needed to create a Power-on Reset. A maximum rise time for V_{DD} is specified. See Electrical Specifications for details.

When the device starts normal operation (exits the RESET condition), device operating parameters (voltage, frequency, temperature,...) must be met to ensure operation. If these conditions are not met, the device must be held in RESET until the operating conditions are met. Brown-out Reset may be used to meet the start-up conditions. For additional information, refer to Application Note, AN007, “Power-up Trouble Shooting”, (DS00007).

12.5 Power-up Timer (PWRT)

The Power-up Timer provides a fixed 72 ms nominal time-out on power-up only from the POR. The Power-up Timer operates on an internal RC oscillator. The chip is kept in RESET as long as the PWRT is active. The PWRT’s time delay allows V_{DD} to rise to an acceptable level. A configuration bit is provided to enable/disable the PWRT.

The power-up time delay will vary from chip to chip due to V_{DD}, temperature and process variation. See DC parameters for details (T_{PWRT}, parameter #33).

12.6 Oscillator Start-up Timer (OST)

The Oscillator Start-up Timer (OST) provides a delay of 1024 oscillator cycles (from OSC1 input) after the PWRT delay is over (if PWRT is enabled). This helps to ensure that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or Wake-up from SLEEP.

12.7 Brown-out Reset (BOR)

The configuration bit, BODEN, can enable or disable the Brown-out Reset circuit. If V_{DD} falls below V_{BOR} (parameter D005, about 4V) for longer than T_{BOR} (parameter #35, about 100μS), the brown-out situation will reset the device. If V_{DD} falls below V_{BOR} for less than T_{BOR}, a RESET may not occur.

Once the brown-out occurs, the device will remain in Brown-out Reset until V_{DD} rises above V_{BOR}. The Power-up Timer then keeps the device in RESET for T_{PWRT} (parameter #33, about 72mS). If V_{DD} should fall below V_{BOR} during T_{PWRT}, the Brown-out Reset process will restart when V_{DD} rises above V_{BOR} with the Power-up Timer Reset. The Power-up Timer is always enabled when the Brown-out Reset circuit is enabled, regardless of the state of the PWRT configuration bit.

12.8 Time-out Sequence

On power-up, the time-out sequence is as follows: The PWRT delay starts (if enabled) when a POR Reset occurs. Then OST starts counting 1024 oscillator cycles when PWRT ends (LP, XT, HS). When the OST ends, the device comes out of RESET.

If $\overline{MCLR}$ is kept low long enough, the time-outs will expire. Bringing $\overline{MCLR}$ high will begin execution immediately. This is useful for testing purposes or to synchronize more than one PIC16F87X device operating in parallel.

Table 12-5 shows the RESET conditions for the STATUS, PCON and PC registers, while Table 12-6 shows the RESET conditions for all the registers.

12.9 Power Control/Status Register (PCON)

The Power Control/Status Register, PCON, has up to two bits depending upon the device.

Bit0 is Brown-out Reset Status bit, $\overline{BOR}$. Bit $\overline{BOR}$ is unknown on a Power-on Reset. It must then be set by the user and checked on subsequent RESETS to see if bit $\overline{BOR}$ cleared, indicating a BOR occurred. When the Brown-out Reset is disabled, the state of the $\overline{BOR}$ bit is unpredictable and is, therefore, not valid at any time.

Bit1 is $\overline{POR}$ (Power-on Reset Status bit). It is cleared on a Power-on Reset and unaffected otherwise. The user must set this bit following a Power-on Reset.

TABLE 12-3: TIME-OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Power-up		Brown-out	Wake-up from SLEEP
	$\overline{PWRTE}$ = 0	$\overline{PWRTE}$ = 1		
XT, HS, LP	72 ms + 1024T_{OSC}	1024T_{OSC}	72 ms + 1024T_{OSC}	1024T_{OSC}
RC	72 ms	—	72 ms	—

12.17 In-Circuit Serial Programming

PIC16F87X microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data and three other lines for power, ground, and the programming voltage. This allows customers to manufacture boards with unprogrammed devices, and then program the microcontroller just before shipping the product. This also allows the most recent firmware, or a custom firmware to be programmed.

When using ICSP, the part must be supplied at 4.5V to 5.5V, if a bulk erase will be executed. This includes reprogramming of the code protect, both from an on-state to off-state. For all other cases of ICSP, the part may be programmed at the normal operating voltages. This means calibration values, unique user IDs, or user code can be reprogrammed or added.

For complete details of serial programming, please refer to the EEPROM Memory Programming Specification for the PIC16F87X (DS39025).

12.18 Low Voltage ICSP Programming

The LVP bit of the configuration word enables low voltage ICSP programming. This mode allows the microcontroller to be programmed via ICSP using a V_{DD} source in the operating voltage range. This only means that V_{PP} does not have to be brought to V_{IHH}, but can instead be left at the normal operating voltage. In this mode, the RB3/PGM pin is dedicated to the programming function and ceases to be a general purpose I/O pin. During programming, V_{DD} is applied to the $\overline{MCLR}$ pin. To enter Programming mode, V_{DD} must be applied to the RB3/PGM, provided the LVP bit is set. The LVP bit defaults to on (‘1’) from the factory.

Note 1: The High Voltage Programming mode is always available, regardless of the state of the LVP bit, by applying V_{IHH} to the $\overline{MCLR}$ pin.

2: While in Low Voltage ICSP mode, the RB3 pin can no longer be used as a general purpose I/O pin.

3: When using low voltage ICSP programming (LVP) and the pull-ups on PORTB are enabled, bit 3 in the TRISB register must be cleared to disable the pull-up on RB3 and ensure the proper operation of the device.

4: RB3 should not be allowed to float if LVP is enabled. An external pull-down device should be used to default the device to normal operating mode. If RB3 floats high, the PIC16F87X device will enter Programming mode.

5: LVP mode is enabled by default on all devices shipped from Microchip. It can be disabled by clearing the LVP bit in the CONFIG register.

6: Disabling LVP will provide maximum compatibility to other PIC16CXXX devices.

If Low Voltage Programming mode is not used, the LVP bit can be programmed to a '0' and RB3/PGM becomes a digital I/O pin. However, the LVP bit may only be programmed when programming is entered with V_{IHH} on $\overline{MCLR}$. The LVP bit can only be charged when using high voltage on $\overline{MCLR}$.

It should be noted, that once the LVP bit is programmed to 0, only the High Voltage Programming mode is available and only High Voltage Programming mode can be used to program the device.

When using low voltage ICSP, the part must be supplied at 4.5V to 5.5V, if a bulk erase will be executed. This includes reprogramming of the code protect bits from an on-state to off-state. For all other cases of low voltage ICSP, the part may be programmed at the normal operating voltage. This means calibration values, unique user IDs, or user code can be reprogrammed or added.

15.1 DC Characteristics: PIC16F873/874/876/877-04 (Commercial, Industrial) PIC16F873/874/876/877-20 (Commercial, Industrial) PIC16LF873/874/876/877-04 (Commercial, Industrial) (Continued)

PIC16LF873/874/876/877-04 (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial 0°C ≤ TA ≤ +70°C for commercial				
PIC16F873/874/876/877-04 **PIC16F873/874/876/877-20** (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial 0°C ≤ TA ≤ +70°C for commercial				
Param No.	**Symbol**	**Characteristic/ Device**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	IDD	**Supply Current**(2,5)					
D010		16LF87X	—	0.6	2.0	mA	XT, RC osc configuration FOSC = 4 MHz, VDD = 3.0V
D010		16F87X	—	1.6	4	mA	RC osc configurations FOSC = 4 MHz, VDD = 5.5V
D010A		16LF87X	—	20	35	μA	LP osc configuration FOSC = 32 kHz, VDD = 3.0V, WDT disabled
D013		16F87X	—	7	15	mA	HS osc configuration, FOSC = 20 MHz, VDD = 5.5V
D015	ΔIBOR	**Brown-out Reset Current**(6)	—	85	200	μA	BOR enabled, VDD = 5.0V

Legend: Rows with standard voltage device data only are shaded for improved readability.

† Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading, switching rate, oscillator type, internal code execution pattern and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD;
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

7: When BOR is enabled, the device will operate correctly until the VBOR voltage trip point is reached.

FIGURE 15-6: EXTERNAL CLOCK TIMING

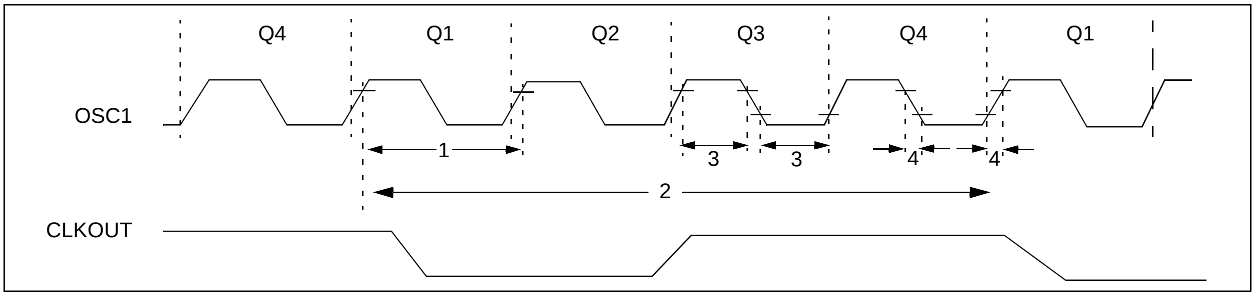


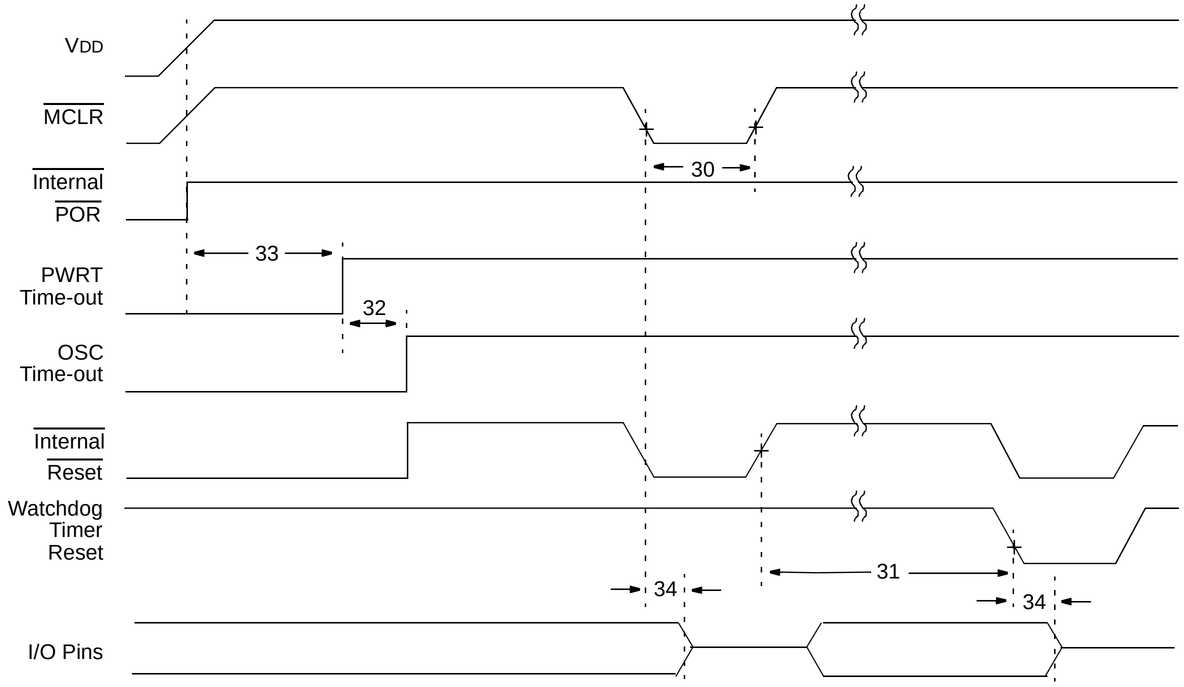
TABLE 15-1: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	FOSC	External CLKIN Frequency **(Note 1)**	DC	—	4	MHz	XT and RC osc mode
			DC	—	4	MHz	HS osc mode (-04)
			DC	—	10	MHz	HS osc mode (-10)
			DC	—	20	MHz	HS osc mode (-20)
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency **(Note 1)**	DC	—	4	MHz	RC osc mode
			0.1	—	4	MHz	XT osc mode
			4	—	10	MHz	HS osc mode (-10)
			4	—	20	MHz	HS osc mode (-20)
			5	—	200	kHz	LP osc mode
1	TOSC	External CLKIN Period **(Note 1)**	250	—	—	ns	XT and RC osc mode
			250	—	—	ns	HS osc mode (-04)
			100	—	—	ns	HS osc mode (-10)
			50	—	—	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
		Oscillator Period **(Note 1)**	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	—	ns	HS osc mode (-04)
			100	—	250	ns	HS osc mode (-10)
			50	—	250	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
2	TCY	Instruction Cycle Time **(Note 1)**	200	TCY	DC	ns	TCY = 4/FOSC
3	TosL, TosH	External Clock in (OSC1) High or Low Time	100	—	—	ns	XT oscillator
			2.5	—	—	μs	LP oscillator
			15	—	—	ns	HS oscillator
4	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	—	—	25	ns	XT oscillator
			—	—	50	ns	LP oscillator
			—	—	15	ns	HS oscillator

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions, with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "max." cycle time limit is "DC" (no clock) for all devices.

FIGURE 15-8: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING



Note: Refer to Figure 15-5 for load conditions.

FIGURE 15-9: BROWN-OUT RESET TIMING

TABLE 15-3: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER, AND BROWN-OUT RESET REQUIREMENTS

Parameter No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
30	TmcL	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	μs	VDD = 5V, -40°C to +85°C
31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	VDD = 5V, -40°C to +85°C
32	Tost	Oscillation Start-up Timer Period	—	1024 TOSC	—	—	TOSC = OSC1 period
33*	Tpwrt	Power-up Timer Period	28	72	132	ms	VDD = 5V, -40°C to +85°C
34	TIOZ	I/O Hi-impedance from $\overline{\text{MCLR}}$ Low or Watchdog Timer Reset	—	—	2.1	μs	
35	TBOR	Brown-out Reset pulse width	100	—	—	μs	VDD ≤ VBOR (D005)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 16-15: AVERAGE WDT PERIOD vs. VDD OVER TEMPERATURE (-40°C TO 125°C)

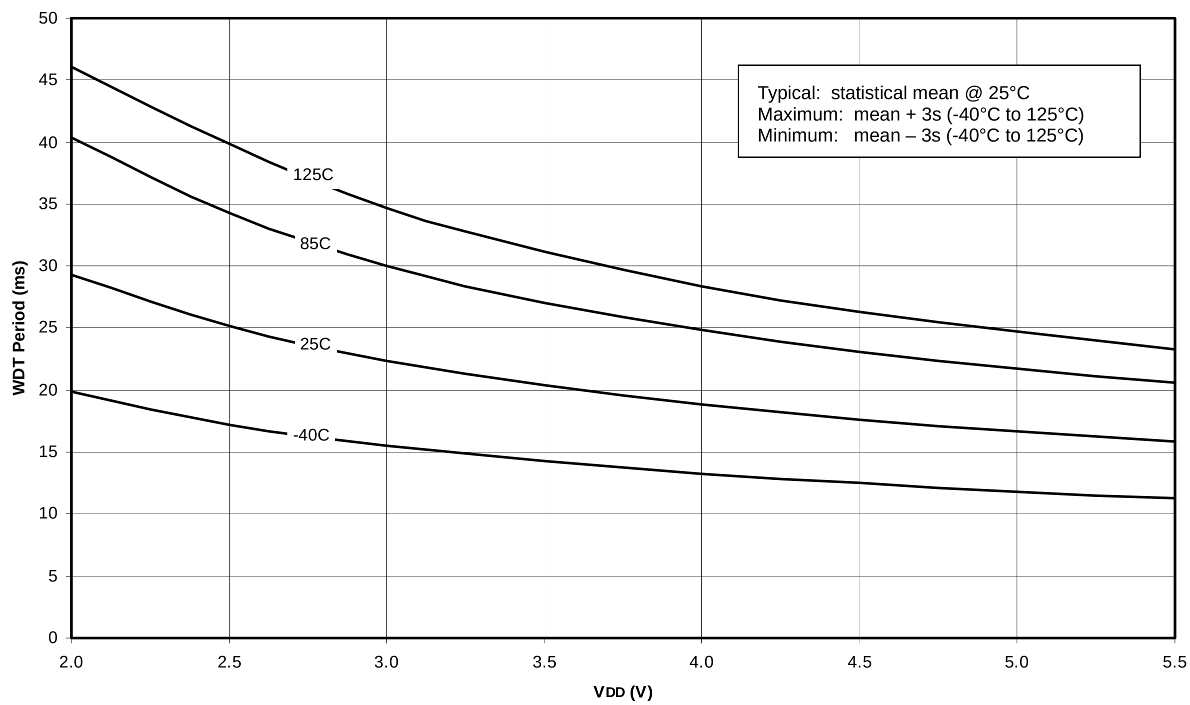
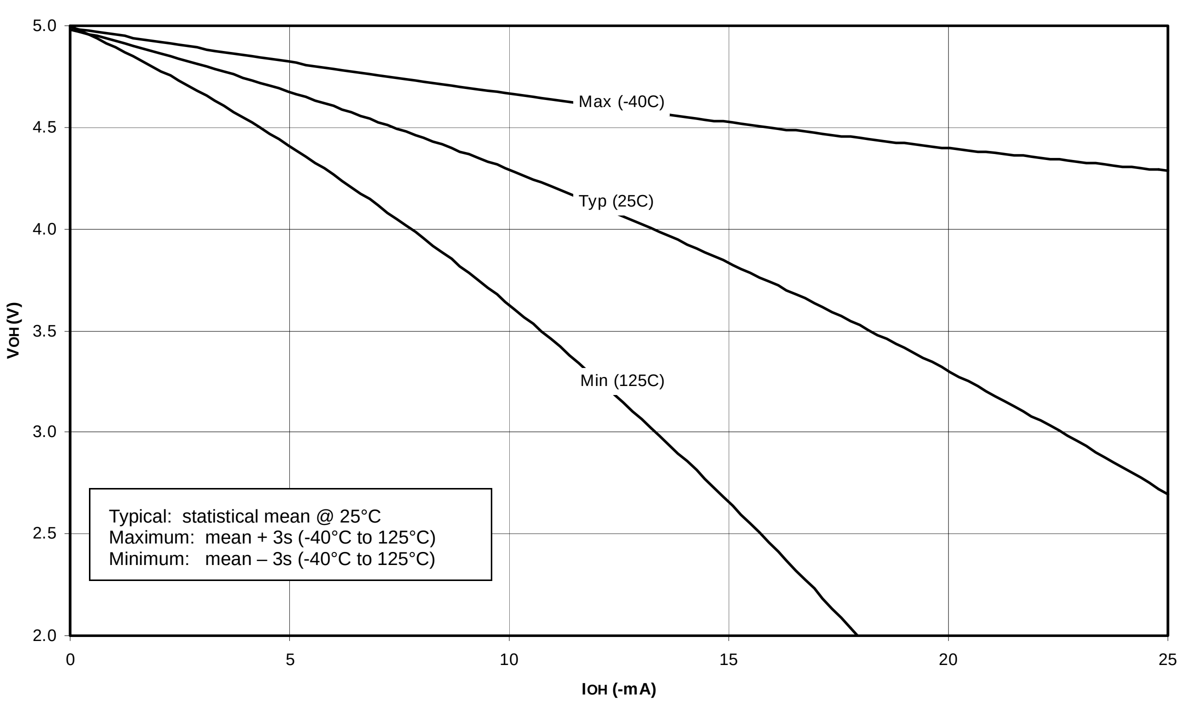
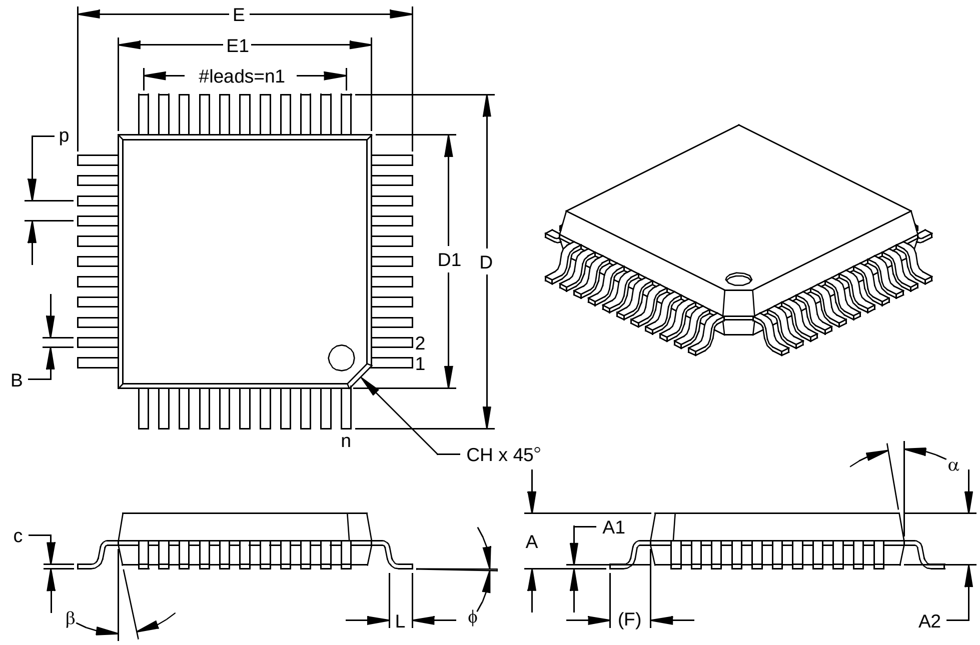


FIGURE 16-16: TYPICAL, MINIMUM AND MAXIMUM VOH vs. IOH (VDD=5V, -40°C TO 125°C)



44-Lead Plastic Metric Quad Flatpack (PQ) 10x10x2 mm Body, 1.6/0.15 mm Lead Form (MQFP)

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES			MILLIMETERS*		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		44			44	
Pitch	p		.031			0.80	
Pins per Side	n1		11			11	
Overall Height	A	.079	.086	.093	2.00	2.18	2.35
Molded Package Thickness	A2	.077	.080	.083	1.95	2.03	2.10
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25
Foot Length	L	.029	.035	.041	0.73	0.88	1.03
Footprint (Reference)	(F)		.063			1.60	
Foot Angle	φ	0	3.5	7	0	3.5	7
Overall Width	E	.510	.520	.530	12.95	13.20	13.45
Overall Length	D	.510	.520	.530	12.95	13.20	13.45
Molded Package Width	E1	.390	.394	.398	9.90	10.00	10.10
Molded Package Length	D1	.390	.394	.398	9.90	10.00	10.10
Lead Thickness	c	.005	.007	.009	0.13	0.18	0.23
Lead Width	B	.012	.015	.018	0.30	0.38	0.45
Pin 1 Corner Chamfer	CH	.025	.035	.045	0.64	0.89	1.14
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.
JEDEC Equivalent: MS-022
Drawing No. C04-071

INDEX